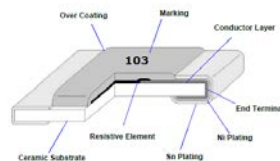


MATERIAL DECLARATION SHEET



Material Number	CRL1206 series		
Product Line	Thick Film Low Ohmic Chip Resistors		
Compliance Date	04-01-2003		
RoHS Compliant	Yes	MSL	1



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00779	Aluminum oxide	1344-28-1	96%	87.04	90.67
				Silicon dioxide	14808-60-7	4%	3.63	
2	Conductor Layer	Thick Film Conductor	0.00015	Silver	7440-22-4	96%	1.63	1.71
				Bismuth	7440-69-9	1%	0.02	
				Barium	7440-39-3	1%	0.02	
				Silicon	7440-21-3	1%	0.02	
				Boron	7440-42-8	1%	0.02	
3	Resistive Element	Thick Film Resistor	0.0001	Ruthenium dioxide	12036-10-1	25%	0.28	1.11
				Silver	7440-22-4	40%	0.44	
				Palladium	7440-05-3	15%	0.17	
				Lead	7439-92-1	20%	0.22	
4	Over Coating	Epoxy	0.00011	Epoxy	29690-82-2	100%	1.32	1.32
5	Marking	Epoxy	0.000013	Epoxy	25085-99-8	100%	0.15	0.15
6	End Terminal	NI-CR	0.000007	Nickel	7440-02-0	80%	0.06	0.08
				Chromium	7440-47-3	20%	0.02	
7	Ni Plating	Nickel	0.00023	Nickel	7440-02-0	100%	2.7	2.7
8	Sn Plating	Tin	0.00019	Tin	7440-31-5	100%	2.26	2.26
			Total weight	0.00859				

This Document was updated on: 2016-2-5

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I.